



Multichip Die Bonder 2200 evo
The Future of Advanced Packaging
Available Today



Innovative Solution for Innovative Products

Current trends in electronics are leading to an ever greater variety of functions, which are often implemented with systems-in-a-package (SiP) for short innovation cycles at low cost. For this purpose, evolutionary manufacturing equipment assembles all kinds of technologies on a tried-and-tested platform with high precision, to produce highly integrated packages with optimized costs, small dimensions, and excellent performance features.

Datacon's 2200 evo will suit your laboratory development and high-volume production needs perfectly and will grow with your requirements.

Performance

With a placement accuracy of $\pm 7\mu\text{m}$ @ 3 Sigma and a throughput of up to 7,000 chips per hour the 2200 evo sets new standards for versatile equipment, usable for many different multichip applications like hybrid, stacked die, SiP/CMOS or thin dies.

Versatility

This overall new system provides the ultimate flexibility for die attach as well as for flip chip applications. Equipped with integrated dispenser, SEMI-standard 12" wafer handling, pick-and-place tool changer, multichip ejector carousel, various I/O systems and application specific tooling, the 2200 evo is prepared for present and future processes and products. Up to 25 different wafers can be processed in one production cycle with automatic feed. Thanks to modular design, the equipment adjusts smoothly to growing production volumes.

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High Performance at High Accuracy

- Highest accuracy $\pm 7\mu\text{m}$ @ 3 Sigma
- High productivity, low cost-of-ownership
- Up to 4 working heads in one machine

Multichip Capability

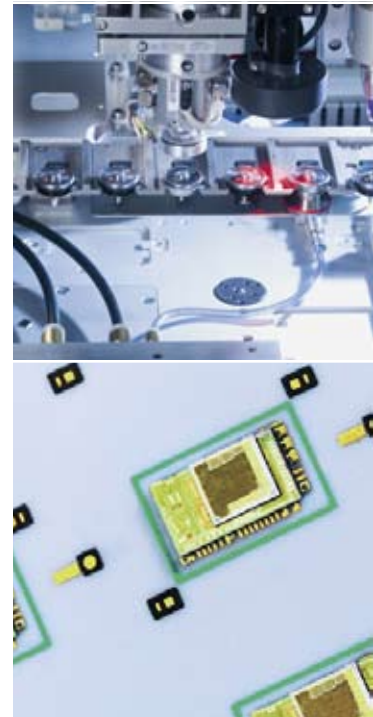
- Single pass production for complex products
- Die attach, flip chip, multichip in one machine
- Epoxy writing & stamping, flux dipping

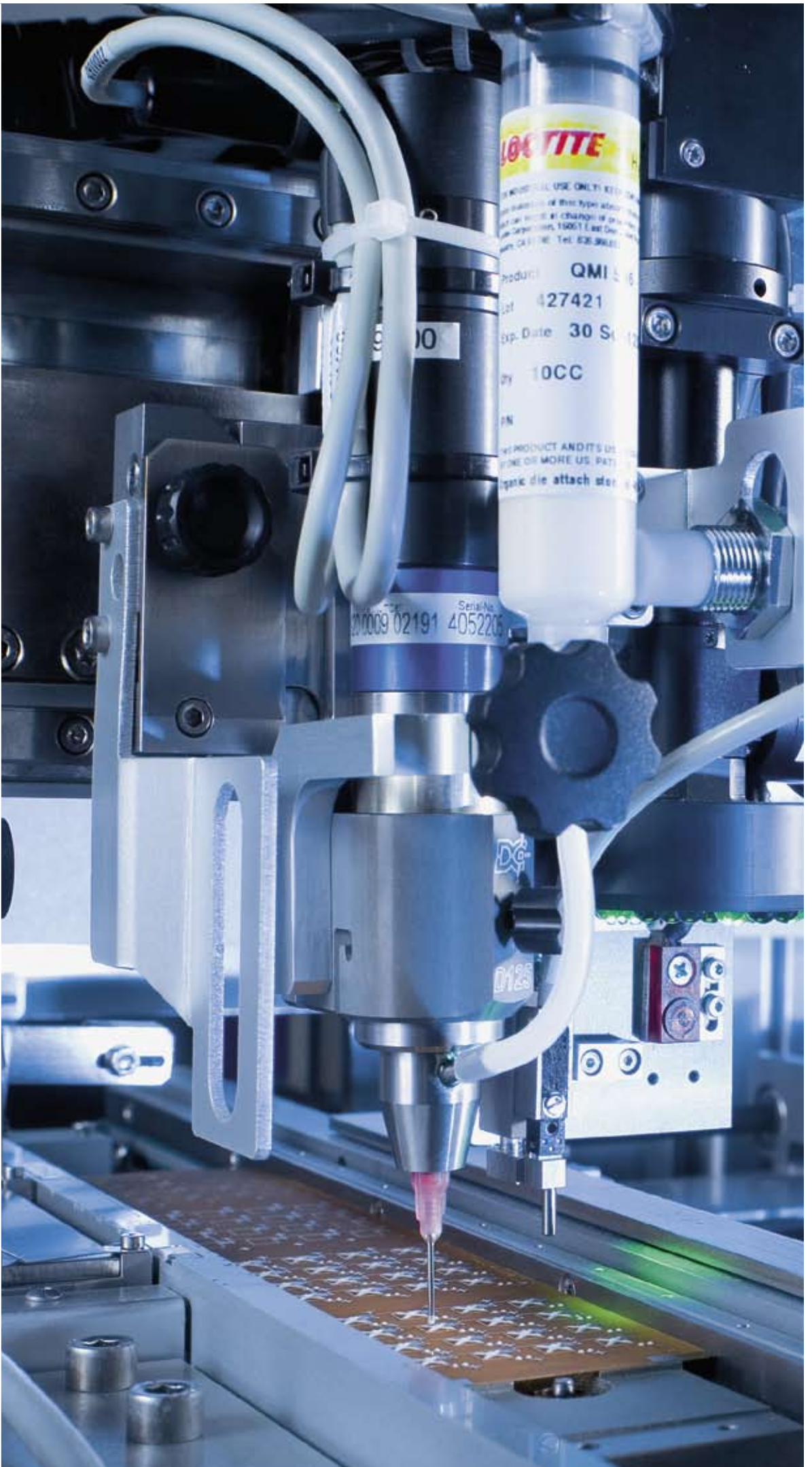
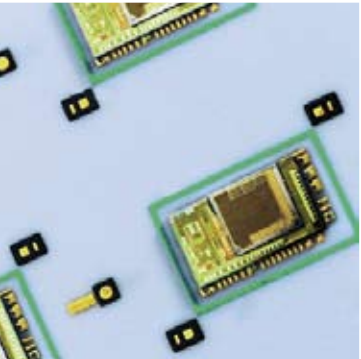
Unbeaten Flexibility

- Die pick from wafer, waffle pack, gel pack, feeder
- Die place to carrier, boat, substrate, PCB, lead frame, wafer
- Hot and cold processes supported: epoxy, soldering, thermo-compression
- MCM, SiP, Hybrids

Open platform architecture for full customization

- Most advanced modular platform concept
- Production line tailored 100% to your needs
- Ideal solution with smallest footprint possible





To the limits. And beyond.

Breaking New Ground since 1986

Since its early beginnings in 1986, Datacon has been breaking new ground in the IC manufacturing and packaging industry. Datacon's main area of expertise is the development and production of high-precision assembly equipment for the microchip industry. Leading microelectronics companies worldwide, such as Bosch, Fairchild, Siemens, Philips, Infineon, ST Micro, Skyworks and Asian subcontractors like Amkor, ASE and STATS-ChipPAC are among Datacon's customers.

Using a highly adaptable platform concept with modular systems, Datacon's product range offers a large degree of flexibility and modularity for the IC manufacturing industry. Datacon is one of the leading and most

innovative providers of assembly equipment for the semiconductor industry and is ahead of the field when it comes to new technologies such as flip chip and RFID (non-contact data transmission). Offering dynamic, flexible concept strategies and latest technologies, Datacon is known in the die bonder market as a solution supplier and an essential research partner for the semiconductor industry worldwide.

Serving the Semiconductor Industry

Datacon has been part of the Dutch Besi group (BE Semiconductor Industries N.V.) since early 2005. Besi and its subsidiaries form a leading group of manufacturers of semiconductor die sorting, flip chip and multichip die bonding, wire bonding, packag-

ing and plating equipment, for both array connect and leadframe assembly processes. Our technologically advanced equipment and integrated systems are used principally to produce semiconductor assemblies or "packages", which provide the electronic interface and physical connection between the chip and other electronic components and protect the chip from the external environment. Our innovative systems offer customers high productivity and improved yields from defect-free devices at a low total-cost-of-ownership.

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